

# 2SJ0536

## Silicon P-channel MOSFET

Secondary battery packs (Li ion battery, etc.)  
For switching circuits

### ■ Features

- High-speed switching
- S-mini type package, allowing downsizing of the sets and automatic insertion through the tape/magazine packing
- Low voltage drive ( $V_{th}$ : -1.0 V to 2.0 V)
- Low ON resistance

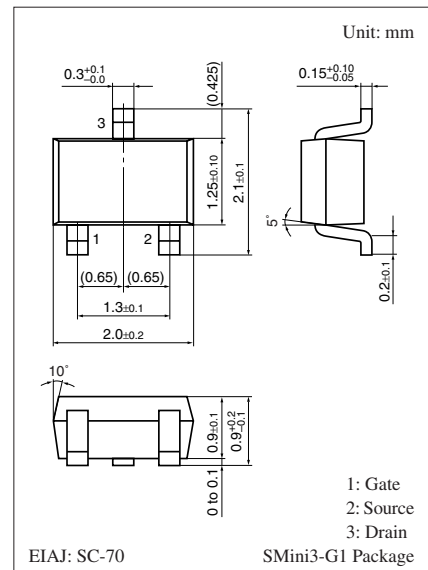
### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Drain-source surrender voltage	$V_{DSS}$	-30	V
Gate-source voltage (Drain open)	$V_{GSO}$	$\pm 20$	V
Drain current	$I_D$	-100	mA
Peak drain current	$I_{DP}$	-200	mA
Power dissipation	$P_D$	150	mW
Channel temperature	$T_{ch}$	150	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to +150	$^\circ\text{C}$

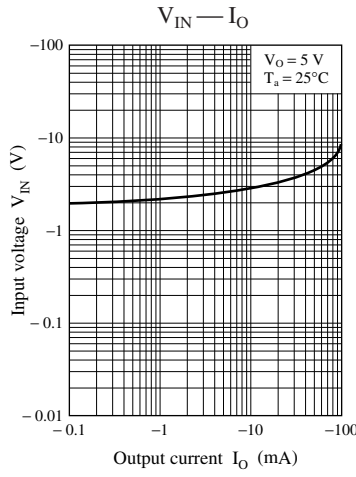
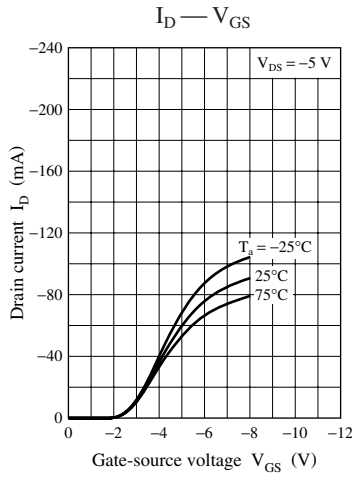
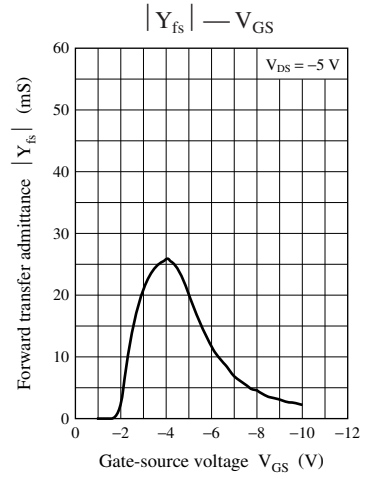
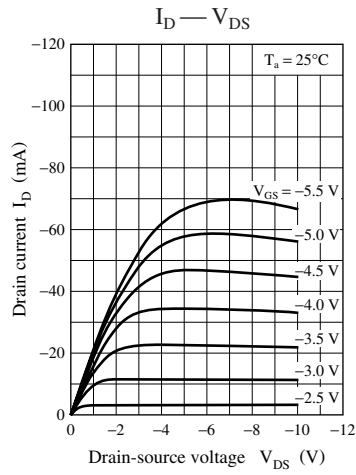
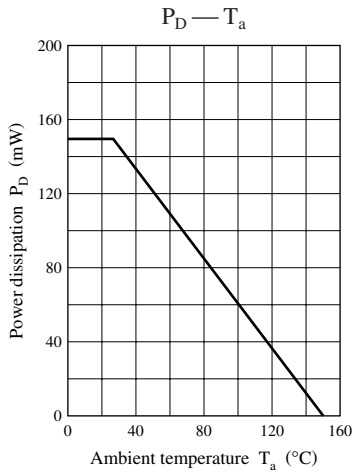
### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Drain-source cutoff current	$I_{DSS}$	$V_{DS} = -30\text{ V}, V_{GS} = 0$			-0.1	$\mu\text{A}$
Gate-source cutoff current	$I_{GSS}$	$V_{GS} = \pm 20\text{ V}, V_{DS} = 0$			$\pm 1.0$	$\mu\text{A}$
Gate threshold voltage	$V_{th}$	$V_{DS} = -5\text{ V}, I_D = -1\ \mu\text{A}$	-1.0		-2.0	V
Forward transfer admittance	$ Y_{fs} $	$V_{DS} = -5\text{ V}, I_D = -10\text{ mA}$	8			mS
Drain-source ON resistance	$R_{DS(on)}$	$V_{GS} = -5\text{ V}, I_D = -10\text{ mA}$		50	75	$\Omega$
Turn-on time	$t_{on}$	$V_{DD} = -5\text{ V}, V_{GS} = 0\text{ V} \sim -5\text{ V}$ $R_L = 200\ \Omega$		100		$\mu\text{s}$
Turn-off time	$t_{off}$	$V_{DD} = -5\text{ V}, V_{GS} = -5\text{ V} \sim 0\text{ V}$ $R_L = 200\ \Omega$		25		$\mu\text{s}$

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.  
2. Observe precautions for handling. Electrostatic sensitive devices.



Marking Symbol: 2C



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